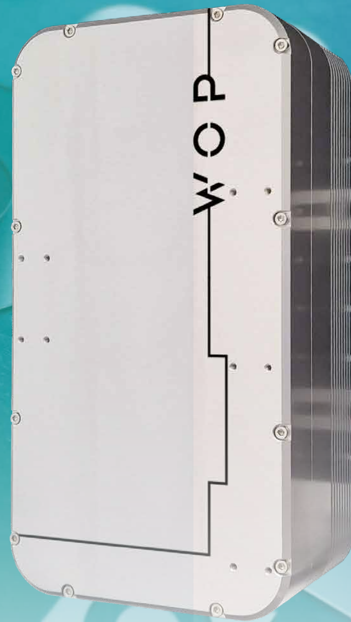
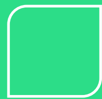


WOP Transparent Material Cutting Module

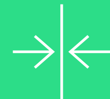
Unique laser technology for industrial glass, sapphire, and other brittle materials cutting, developed by WOP | Workshop of Photonics.

Based on WOP patented technology, it stands out for ultra-high precision and quality results, outperforming other glass cutting methods.

High speed


Irregular shapes

Ultra-high precision results


Thin glass & sapphire

Key Features:

- High process speed up to 800 mm/s
- Ultra-thin (30 μm to 3 mm) glass & sapphire cutting
- Tempered, non-tempered glass, sapphire, and other brittle materials cutting
- Irregular shapes
- Inner and outer contours
- Easy breaking for non-tempered and self-breaking for tempered glass.
- High bending strength
- Low chipping < 10 μm
- Smooth sidewalls after breaking, Ra < 1 μm

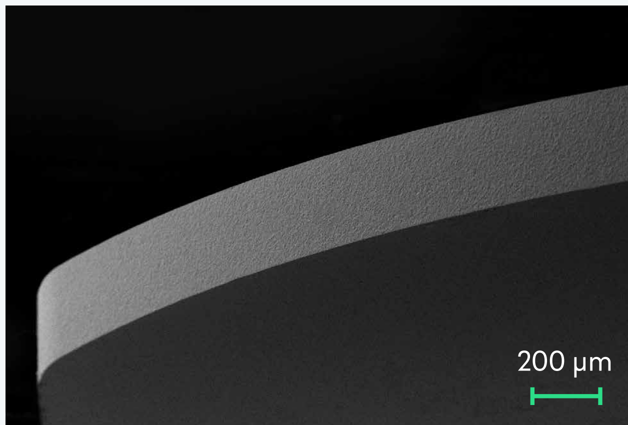
Advantages:

- Compatible with various femtosecond lasers
- Outperforms other glass cutting methods
- Patented technology
- Easy to integrate

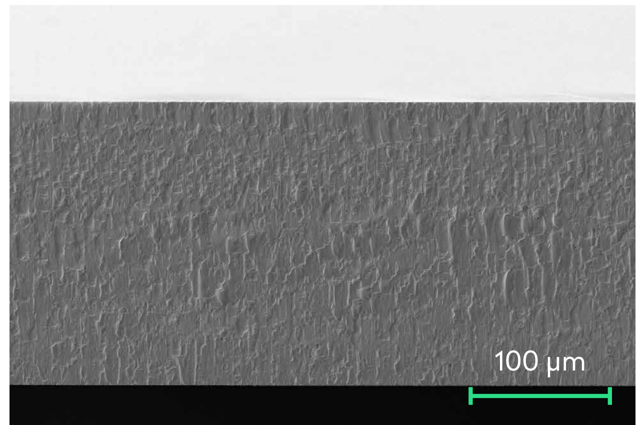
For system integrators:

- Optimized for 1028-1064 nm wavelength (515-532 on request)
- Sealed monolithic housing
- Optional external Machine vision unit
- Optional alignment module for adjustment
- Packages include an optical module and a technology license
- Dimensions HxWxD: 266x140x95 mm

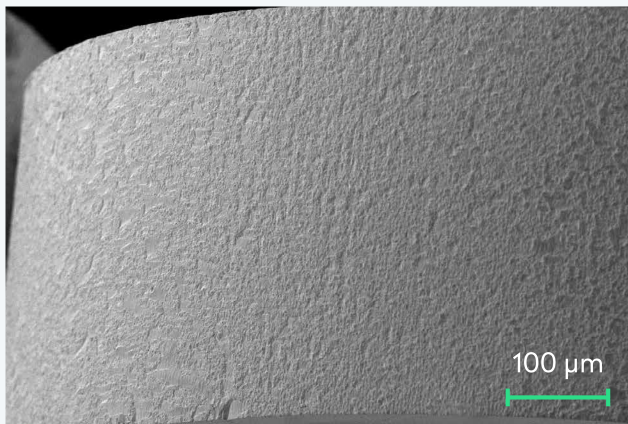
Integrated module | FemtoGLASS laser system



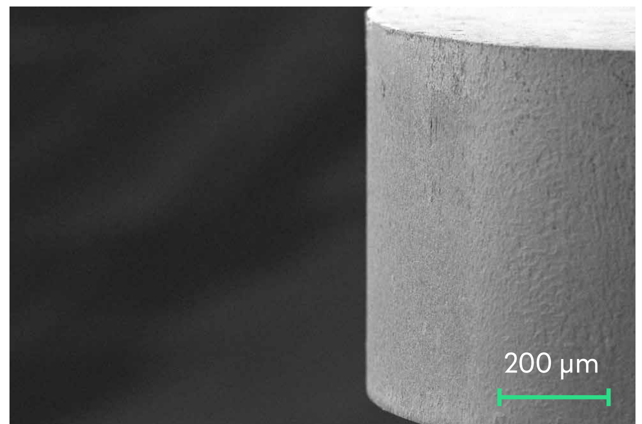
D263T glass, thickness 300 µm



Fused silica glass, thickness 250 µm

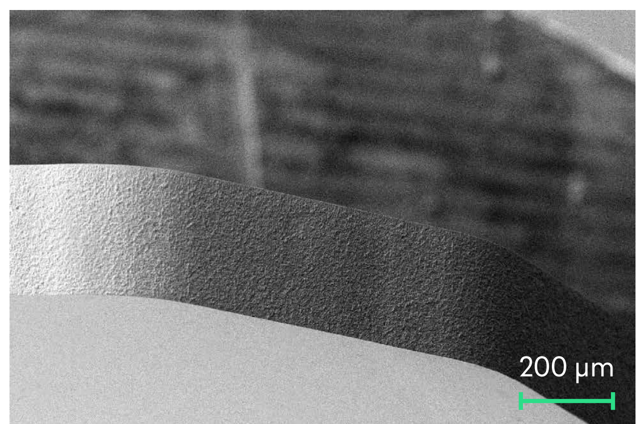


Sapphire, thickness 400 µm



Sapphire, thickness 700 µm

www.wophotonics.com
Mokslininkų st. 6A, Vilnius LT-08412 Lithuania
sales@wophotonics.com



D263T glass, thickness 300 µm